GaAs HEMT

# **HITACHI**

ADE-208-400 1st. Edition

### **Application**

UHF low noise amplifier

#### **Features**

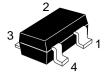
- Excellent low noise characteristics. Fmin = 0.83 dB Typ. (3 V, 10 mA, 2 GHz)
- High associated gain.

Ga = 17 dB Typ. (3 V, 10 mA, 2 GHz)

- High voltage.
  - $V_{DS} = 6$  or more voltage.
- Small package. (CMPAK-4)

#### **Outline**

CMPAK-4



- 1. Source
- 2. Gate
- 3. Source
- 4. Drain



## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit	
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	6	V	
Gate to source voltage	$V_{\rm GSO}$	-6	V	
Gate to drain voltage	$V_{\text{GDO}}$	<b>–</b> 7	V	
Drain current	$I_{D}$	20	mA	
Channel power dissipation	Pch	100	mW	
Channel temperature	Tch	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

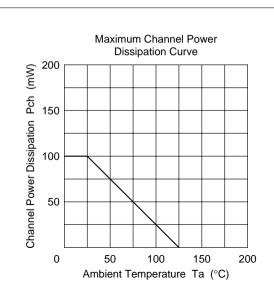
Attention: This device is very sensitive to electro static discharge.

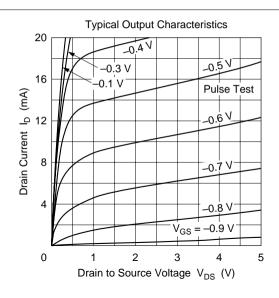
It is recommended to adopt appropriate cautions when handling this transistor.

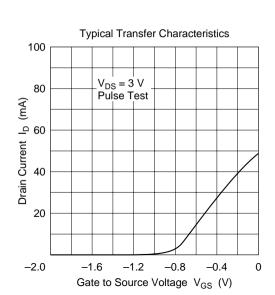
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

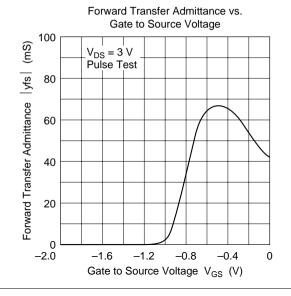
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Gate to source leak current	I <sub>GSS</sub>	_	_	-20	μΑ	$V_{GS} = -6 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V <sub>GS(off)</sub>	-0.3	_	-2.0	V	$V_{DS} = 3 \text{ V}, I_{D} = 100 \mu\text{A}$
Drain current	I <sub>DSS</sub>	35	50	70	mA	$V_{DS} = 3 \text{ V}, V_{GS} = 0$ (Pulse Test)
Forward transfer admittance	y <sub>fs</sub>	40	60	_	mS	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA},$ f = 1 kHz
Associated gain	Ga	_	17.0	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA},$ f = 2 GHz
Associated gain	Ga	_	15.2	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 3 \text{ mA},$ f = 2 GHz
Associated gain	Ga	16	21.4	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA},$ f = 900 MHz
Associated gain	Ga	_	19.7	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 3 \text{ mA},$ f = 900 MHz
Minimum noise figure	Fmin	_	0.83	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA},$ f = 2 GHz
Minimum noise figure	Fmin	_	1.08	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 3 \text{ mA},$ f = 2 GHz
Minimum noise figure	Fmin	_	0.52	1.0	dB	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA},$ f = 900 MHz
Minimum noise figure	Fmin	_	0.74	_	dB	$V_{DS} = 3 \text{ V}, I_{D} = 3 \text{ mA},$ f = 900 MHz

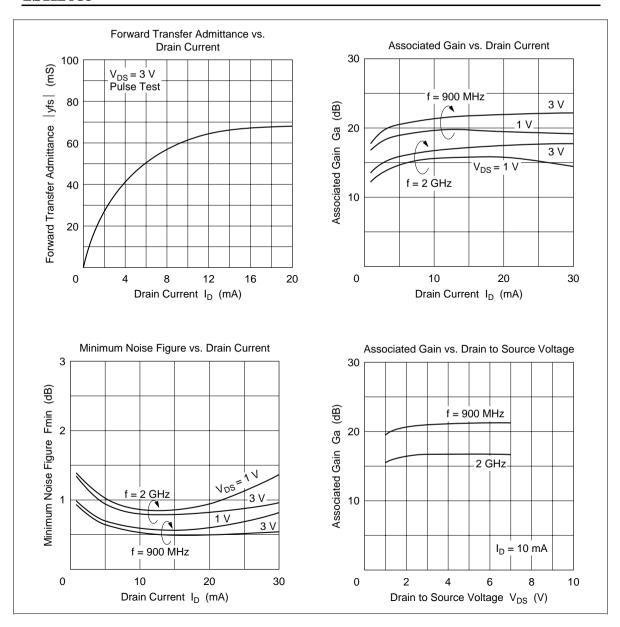
Note: Marking is "ZT-".

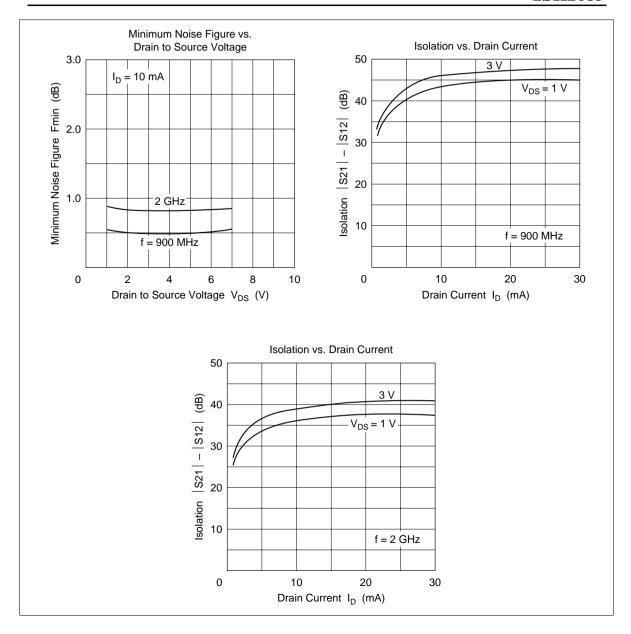


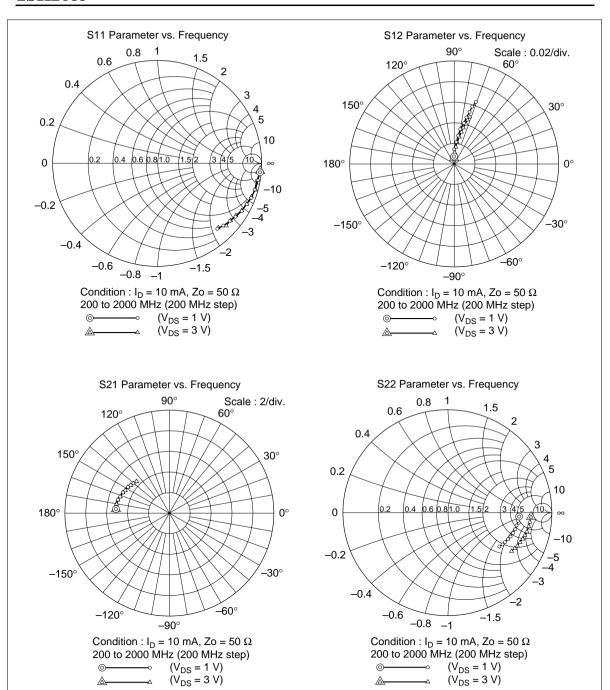












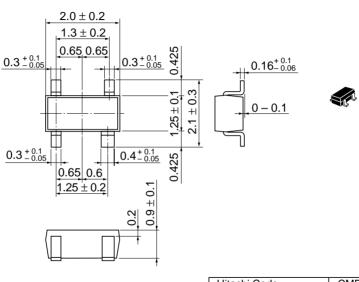
## S Parameter ( $V_{DS} = 1 \text{ V}$ , $I_D = 10 \text{ mA}$ , $Z_O = 50$ )

Freq.	S11		S21		S12		S22	
(MHz)	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.
200	0.996	-4.8	5.12	175.8	0.00691	89.8	0.688	-3.2
400	0.980	-9.5	5.13	169.9	0.0143	88.2	0.682	-6.5
600	0.977	-15.0	5.07	165.4	0.0210	83.3	0.674	-10.6
800	0.970	-19.9	4.94	161.6	0.0276	81.5	0.668	-13.8
1000	0.952	-24.4	4.84	156.5	0.0399	79.3	0.658	-17.2
1200	0.938	-29.2	4.74	152.7	0.0404	76.0	0.648	-20.7
1400	0.916	-34.0	4.67	147.7	0.0462	74.8	0.636	-23.7
1600	0.896	-38.2	4.55	144.1	0.0523	73.1	0.622	-27.1
1800	0.882	-42.9	4.47	140.0	0.0578	72.0	0.611	-29.9
2000	0.859	-47.1	4.36	135.8	0.0630	70.3	0.597	-33.1

## S Parameter ( $V_{DS}=3~V,\,I_{D}=10~mA,\,Z_{O}=50~\Omega)$

Freq.	S11		S21		S12		S22	
(MHz)	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.
200	0.998	-4.0	5.13	175.8	0.00581	89.8	0.802	-3.2
400	0.988	-9.2	5.14	170.1	0.0110	85.5	0.796	-6.5
600	0.978	-14.5	5.08	165.2	0.0163	83.3	0.790	-9.8
800	0.968	-19.4	4.95	161.4	0.0216	82.0	0.783	-13.3
1000	0.953	-24.2	4.85	156.4	0.0363	79.2	0.774	-16.4
1200	0.937	-28.7	4.75	152.5	0.0312	76.5	0.764	-19.4
1400	0.917	-33.3	4.68	147.8	0.0358	75.3	0.753	-22.5
1600	0.900	-37.5	4.57	144.0	0.0401	73.2	0.742	-25.4
1800	0.883	-41.9	4.49	140.1	0.0442	72.8	0.731	-28.1
2000	0.858	-46.1	4.37	135.9	0.0477	71.4	0.718	-31.1

Unit: mm



Hitachi Code	CMPAK-4(T)
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.006 g

### **Datasheet Title**

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